

Corporate Overview



AMKOR PHILOSOPHY

We build our business by helping our customers build theirs.

Technology Leaders

WHO WE ARE

Founded in 1968, Amkor's continuous path of improvement, growth and innovation has led us to be a strategic and trusted manufacturing partner for the world's leading semiconductor companies. Our unique expertise in high-volume manufacturing techniques and the ability to solve the technological challenges facing the industry are among our greatest strengths.



Customer demand for highly sophisticated products has made semiconductor packaging a vital contributor to system performance. As one of the world's largest suppliers of outsourced semiconductor advanced packaging design, assembly and test services, Amkor helps make innovative technologies a reality.

OUR PRODUCT PORTFOLIO

Amkor offers more than 1,000 different package formats and sizes. Products range from traditional leadframe ICs for through-hole and surface mounting to the latest chip scale packages (CSP) and ball grid array (BGA) solutions required in high pin count and high density applications.

Our diverse portfolio includes stacked die, wafer level, MEMS, flip chip, Through Silicon Via (TSV) and 2.5/3D packaging, allowing us to be a single source for many of our customers. We fulfill total semiconductor packaging requirements from legacy devices to System in Package (SiP) solutions. The availability of high quality packaging services allows customers to focus their resources on semiconductor design and wafer fabrication while utilizing Amkor as their packaging technology innovator and test partner.

SPEEDING TIME TO MARKET

Amkor's operations encompass more than 11M ft² of floor space with production facilities, product development centers, sales and support offices strategically located in key electronics manufacturing regions. Our customers benefit from our extensive global footprint, enabling us to easily handle large orders and offer quick turnaround times.

SEMICONDUCTOR IC PACKAGE DESIGN SERVICES

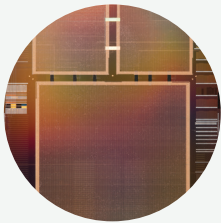
Amkor works closely with substrate and software suppliers to drive next generation package design. Our design engineers are trained experts and experienced in the latest design tools and packaging technology. This enables our World Class Design Centers to reduce design cycle times and provide expert advice.

Products and Services

PACKAGING

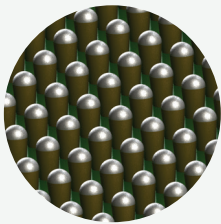
Consumers are demanding greater functionality and performance in a smaller space at a lower cost. Amkor is an industry leader in finding semiconductor packaging solutions to meet these complex requirements.

FEATURED PRODUCTS INCLUDE



2.5/3D – THROUGH SILICON VIA

Through Silicon Via (TSV) interconnects serve a wide range of 2.5D and 3D packaging applications and architectures. TSV meets high performance, low energy demands.



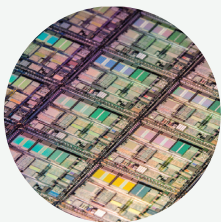
FLIP CHIP

Amkor is committed to being the leading provider of flip chip technology. Flip chip production capability is available in our Korea, Taiwan and China factories.



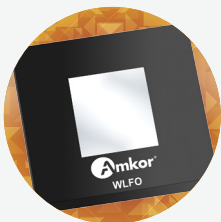
POWER DISCRETES

Optimized for power sensitive and mobile applications, Amkor's high-performance power discrete devices include advanced power packaging, advanced copper clip attach and modules.



SYSTEM IN PACKAGE (SiP)

Industry demands for higher levels of integration and lower costs coupled with a growing awareness of complete system configuration drive the popularity of System in Package (SiP) solutions.



WAFER LEVEL PACKAGING

Amkor offers a broad array of wafer level packaging capabilities and processes for packaging schemes from fan-out to chip scale to 3D to System in Package (SiP).

ASSEMBLY

With global high-volume manufacturing, Amkor assembles a broad portfolio of packaging solutions including wirebond and flip chip using Pb-free and green packaging.

FINAL TEST SERVICES

Amkor provides a complete range of semiconductor test services including various types of final, system level, wafer and strip testing and complete end-of-line services up to and including final shipping.



LOGISTICS AND INVENTORY MANAGEMENT

We provide customers around the world with the electronic components they need to grow their businesses. Amkor offers tape & reel, dry pack and warehousing services with the ability to drop ship products worldwide.

PREPARING FOR THE FUTURE

As the industry moves aggressively to advanced technologies such as 3D stacking of integrated circuits, the complexity of chip package interaction is increasing significantly. Companies look to Amkor to deliver end-to-end solutions that meet the requirements of a broad range of product designs.

Global Technology Leadership

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